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Bambridge 2-7-1-80

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

### Patent Application

Applicant(s): T.B. Bambridge et al.  
Case: 2-7-1-80  
Serial No.: 10/787,010  
Filing Date: February 25, 2004  
Group: 2857  
Examiner: To Be Assigned

Title: Methods and Apparatus for Wire Bonding with  
Wire Length Adjustment in an Integrated Circuit

I hereby certify that this paper is being deposited on this date with the U.S. Postal Service as first class mail addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature: Rosa L. Vulpis Date: July 7, 2004

### INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. §§1.56, 1.97 and 1.98, Applicants' attorney wishes to bring to the attention of the Patent and Trademark Office the following document listed on the accompanying Form PTO-1449: V. Solberg, "Adapting Fine-Line Flex Circuits for 3D Multiple Die Packaging," Semiconductor Manufacturing, pp. 94-108, June 2003. A copy of the listed document is enclosed.

It is believed that there is no fee due in conjunction with the filing of this Information Disclosure Statement. In the event of non-payment or improper payment of a required fee, the Commissioner is authorized to charge or to credit **Ryan, Mason & Lewis, LLP Deposit Account No. 50-0762** as required to correct the error.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, or as an admission that the information cited is considered to be material to patentability, or as a representation that no other material information exists.

Respectfully submitted,



Date: July 7, 2004

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**FORM PTO-1449 (MODIFIED)****LIST OF PUBLICATIONS FOR  
APPLICANT'S INFORMATION  
DISCLOSURE STATEMENT**

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**U.S. PATENT DOCUMENTS**

EXAMINER	DOCUMENT NO.	DATE	NAME	FILING DATE
<u>INITIAL</u>				<u>CLASS/SUBCLASS</u> <u>IF APPROPRIATE</u>

**FOREIGN PATENT DOCUMENTS**

EXAMINER	DOCUMENT NO.	DATE	COUNTRY	TRANSLATION
<u>INITIAL</u>				<u>CLASS/SUBCLASS</u> <u>YES</u> <u>NO</u>

**OTHER DOCUMENTS**

EXAMINER	REF NO.	AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
<u>INITIAL</u>		

— 1. V. Solberg, "Adapting Fine-Line Flex Circuits for 3D Multiple Die Packaging," Semiconductor Manufacturing, pp. 94-108, June 2003.

Examiner

Date Considered

**Examiner:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.